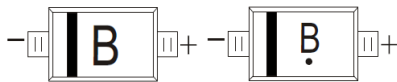


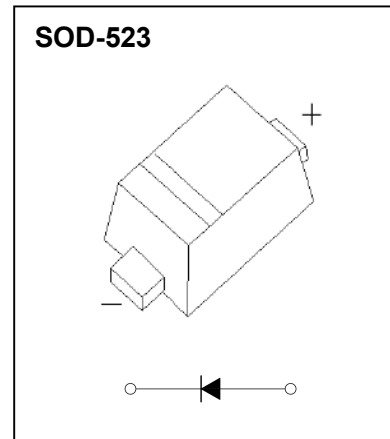
### FEATURES

- Small surface mounting type
- Low  $I_R$
- High reliability

### MARKING: B



The marking bar indicates the cathode  
 Solid dot = Green molding compound device, if none,  
 the normal device.

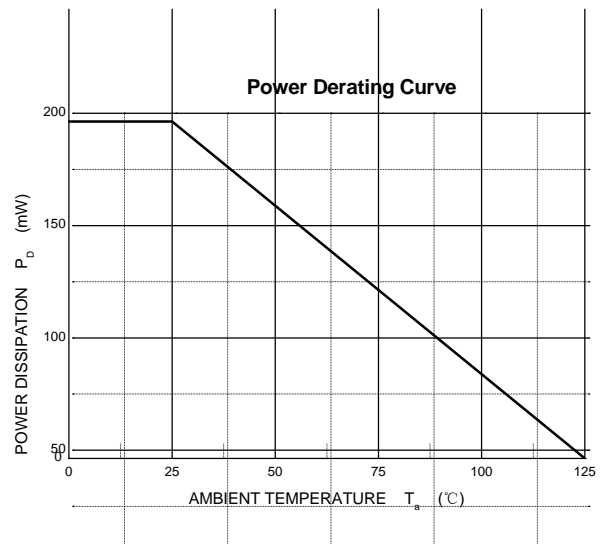
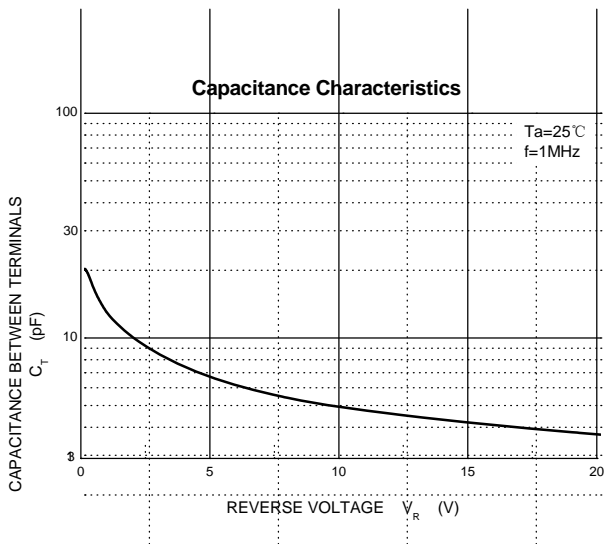
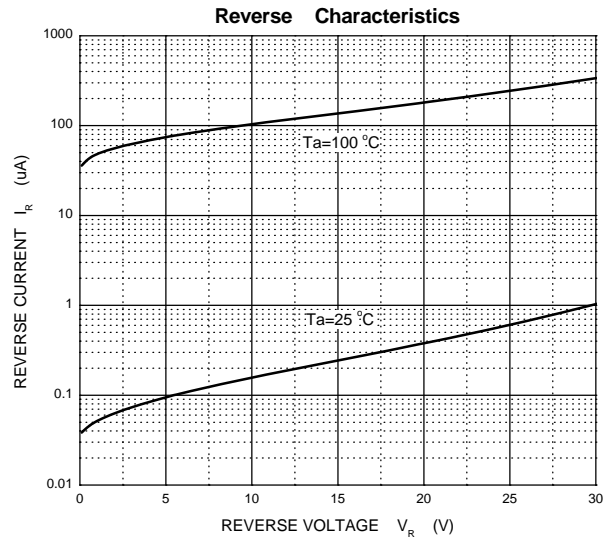
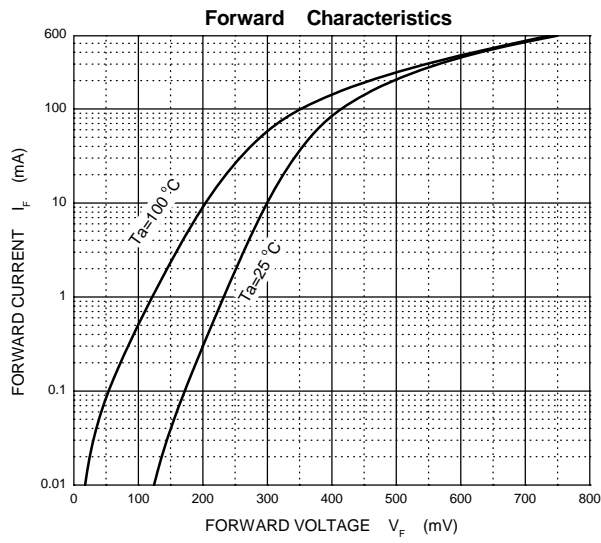


### Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25°C

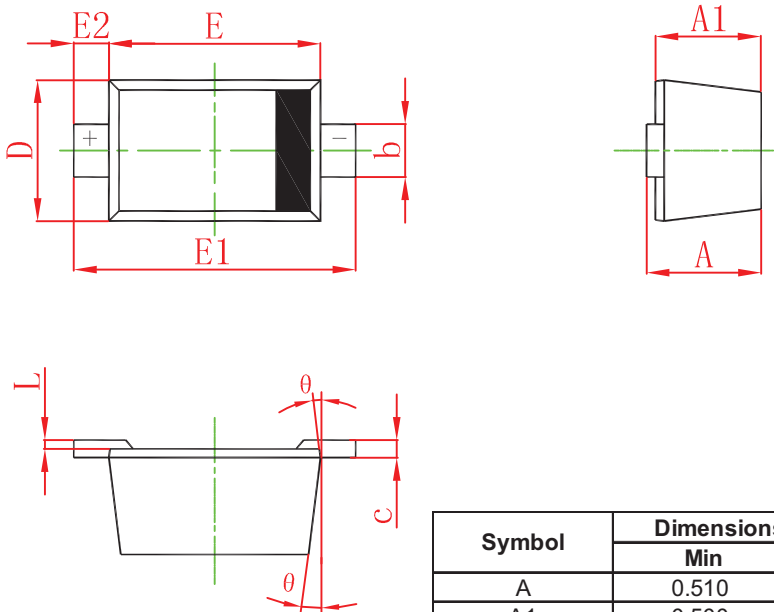
Parameter	Symbol	Limit	Unit
DC reverse voltage	$V_R$	30	V
Mean rectifying current	$I_O$	200	mA
Non-repetitive Peak Forward Surge Current @t=8.3ms	$I_{FSM}$	1	A
Power dissipation	$P_D$	150	mW
Thermal resistance junction to ambient	$R_{\theta JA}$	667	°C/W
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55~+150	°C

### Electrical Ratings @Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Forward voltage	$V_F$			0.6	V	$I_F=200mA$
Reverse current	$I_R$			1	$\mu A$	$V_R=10V$

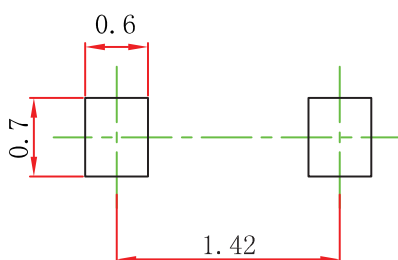


### SOD-523 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

### SOD-523 Suggested Pad Layout



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.